

# SOT1022-1

plastic low profile fine-pitch ball grid array package; 477 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA477
<b>Package type industry code</b>	LFBGA477
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	27-7-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.9	-	12	12.1	mm
E	package width		11.9	-	12	12.1	mm
A	seated height		[tbd]	-	1.45	1.45	mm
A <sub>2</sub>	package height		1	-	1.15	1.15	mm
n <sub>2</sub>	actual quantity of termination		-	-	477	-	



2. Package outline

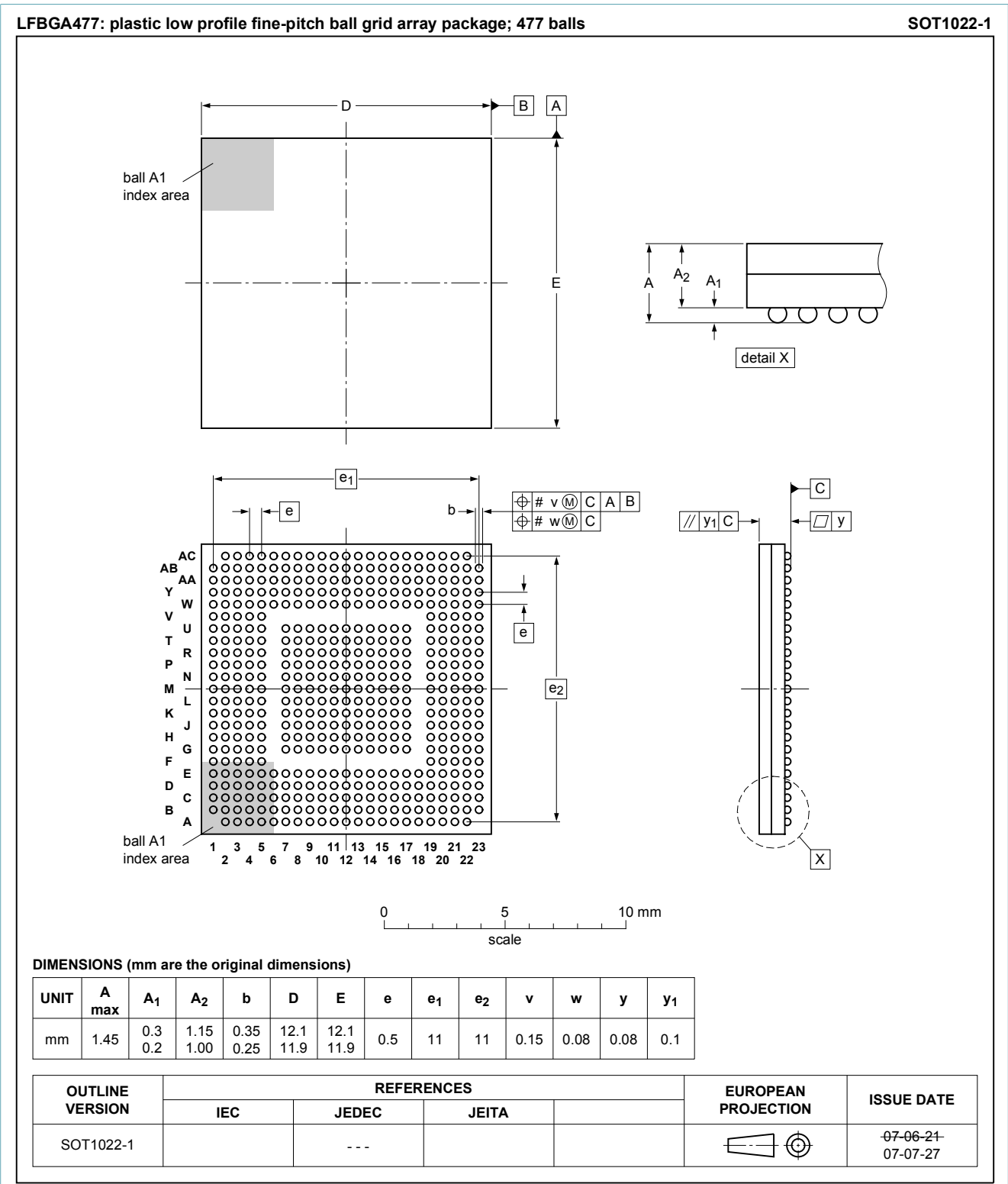


Fig. 1. Package outline LFBGA477 (SOT1022-1)

### 3. Legal information

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